

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZVI OR-BACH	12/01/2020
DEEPAK SEKAR	12/06/2020
RECEIVING PARTY DATA	
Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17114155
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4088399533
Email:	Brian@Monolithic3D.com
Correspondent Name:	BRIAN CRONQUIST
Address Line 1:	1662 COVE POINT RD
Address Line 4:	KLAMATH FALLS, OREGON 97601
ATTORNEY DOCKET NUMBER:	MONOLITHIC3D-9CON7-CDP
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	12/09/2020
Total Attachments: 2	
source=Monolithic3D-9con7-cdp_Assignment_Zvi signed#page1.tif	
source=Monolithic3D-9con7-cdp_Assignment_Deepak bcsignedPOA#page1.tif	

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about December 02, 2020; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, Oregon 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 12.1.20

Zvi Or-Bach

(Zvi

Or-Bach)

First Name

Middle Initial

Last Name

ASSIGNMENT

Whereas, I, **Deepak C. Sekar** (hereinafter referred to as Assignor(s)), residing in **Sunnyvale, California**; have made a certain invention, and executed United States Patent Application entitled:

3D Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about December 02, 2020; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, Oregon 97601 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 6 Dec 2020


 (Deepak C. Sekar)
 First Name Middle Initial Last Name